

Patent Abstracts of Japan

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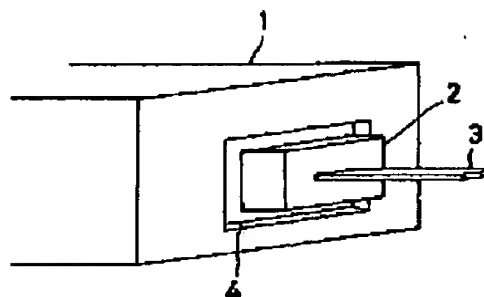
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APPLICANT : NEC CORP;

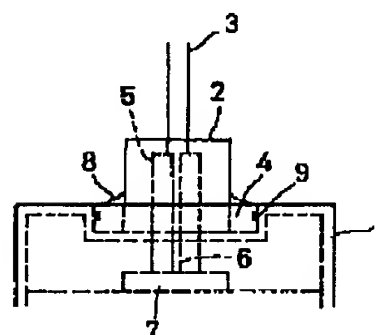
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TITLE : SEALING STRUCTURE OF
ELECTROOPTICAL CONVERSION
MODULE



(b)



ABSTRACT : PURPOSE: To enable applying sealing agent of low viscosity to the sealing of a connection part of an element case for mounting a light emitting element and a light receiving element of an electrooptical conversion module and a cable case for fixing an optical fiber cable, and improve sealing quality.

CONSTITUTION: At the connection part of an element case 1 and a cable case 2, a trench 4 is formed on the element case side, so as to surround the cable case 2. A mark 9 for showing the amount of sealing agent 8 is formed in the trench. Thereby the sealing agent can be made to flow into the trench, so that the sealing agent of low viscosity can be used and sealing quality is improved. By setting the mark so as to show the adequate amount of sealing resin, irregularities due to workers can be prevented.

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